

# XPT IGBT Module

tentative

$$V_{CES} = 2 \times 650V$$

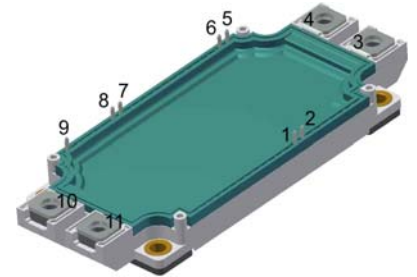
$$I_{C25} = 720A$$

$$V_{CE(sat)} = 1.65V$$

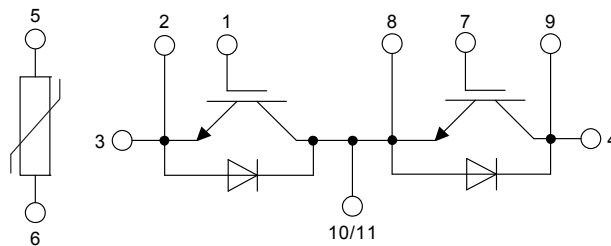
Phase leg + free wheeling Diodes + NTC

Part number

**MIXA600PF650TSF**



Backside: isolated



### Features / Advantages:

- High level of integration - only one power semiconductor module required for the whole drive
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10  $\mu$ sec.
  - very low gate charge
  - low EMI
  - square RBSOA @ 3x  $I_c$
- Thin wafer technology combined with the XPT design results in a competitive low  $V_{CE(sat)}$
- Temperature sense included
- SONIC™ diode
  - fast and soft reverse recovery
  - low operating forward voltage

### Applications:

- AC motor drives
- Pumps, Fans
- Air-conditioning system
- Inverter and power supplies
- UPS

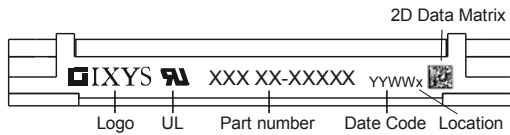
### Package: SimBus F

- Isolation Voltage: 3000V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: Copper internally DCB isolated
- Advanced power cycling

IGBT				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{CES}$	collector emitter voltage	$T_{VJ} = 25^{\circ}C$			650	V	
$V_{GES}$	max. DC gate voltage				$\pm 20$	V	
$V_{GEM}$	max. transient gate emitter voltage				$\pm 30$	V	
$I_{C25}$	collector current	$T_C = 25^{\circ}C$			720	A	
$I_{C80}$		$T_C = 80^{\circ}C$			490	A	
$P_{tot}$	total power dissipation	$T_C = 25^{\circ}C$			1750	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 600A; V_{GE} = 15V$		1.65	1.8	V	
				1.85		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 9.6mA; V_{GE} = V_{CE}$	4	4.8	5.5	V	
$I_{CES}$	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0V$			1.8	mA	
				2		mA	
$I_{GES}$	gate emitter leakage current	$V_{GE} = \pm 20V$			1.5	$\mu A$	
$Q_{G(on)}$	total gate charge	$V_{CE} = 300V; V_{GE} = 15V; I_C = 600A$		840		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 300V; I_C = 600A$ $V_{GE} = \pm 15V; R_G = 1.3\Omega$		30		ns	
$t_r$	current rise time		$T_{VJ} = 150^{\circ}C$		50		ns
$t_{d(off)}$	turn-off delay time				100		ns
$t_f$	current fall time				40		ns
$E_{on}$	turn-on energy per pulse				6		mJ
$E_{off}$	turn-off energy per pulse				22.8		mJ
<b>RBSOA</b>	reverse bias safe operating area	$V_{GE} = \pm 15V; R_G = 1.3\Omega$					
$I_{CM}$		$V_{CEmax} = 650V$			1200	A	
<b>SCSOA</b>	short circuit safe operating area	$V_{CEmax} = 650V$					
$t_{sc}$	short circuit duration	$V_{CE} = 360V; V_{GE} = \pm 15V$			10	$\mu s$	
$I_{sc}$	short circuit current	$R_G = 1.3\Omega; \text{non-repetitive}$		2400		A	
$R_{thJC}$	thermal resistance junction to case				0.085	K/W	
$R_{thCH}$	thermal resistance case to heatsink				0.05	K/W	
<b>Diode</b>							
$V_{RRM}$	max. repetitive reverse voltage	$T_{VJ} = 25^{\circ}C$			650	V	
$I_{F25}$	forward current	$T_C = 25^{\circ}C$			490	A	
$I_{F80}$		$T_C = 80^{\circ}C$			340	A	
$V_F$	forward voltage	$I_F = 600A$			1.90	V	
				1.70		V	
$I_R$	reverse current	$V_R = V_{RRM}$			*	mA	
	* not applicable, see Ices value above				*	mA	
$Q_{rr}$	reverse recovery charge	$V_R = 300V$ $-di_F/dt = 0A/\mu s$ $I_F = 600A; V_{GE} = 0V$		tbd		$\mu C$	
$I_{RM}$	max. reverse recovery current		$T_{VJ} = 125^{\circ}C$		tbd		A
$t_{rr}$	reverse recovery time				tbd		ns
$E_{rec}$	reverse recovery energy				tbd		mJ
$R_{thJC}$	thermal resistance junction to case				0.095	K/W	
$R_{thCH}$	thermal resistance case to heatsink				0.04	K/W	

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Package SimBus F			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal				A
$T_{stg}$	storage temperature		-40		125	°C
$T_{VJ}$	virtual junction temperature		-40		175	°C
<b>Weight</b>				350		g
$M_D$	mounting torque		3		6	Nm
$M_T$	terminal torque		3		6	Nm
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	12.7			mm
$d_{Spb/Apb}$		terminal to backside	10.0			mm
$V_{ISOL}$	isolation voltage	t = 1 second t = 1 minute 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000			V
			2500			V
$R_{pin-chip}$	resistance pin to chip	$V = V_{CEsat} + 2 \cdot R \cdot I_C$ resp. $V = V_F + 2 \cdot R \cdot I_F$		0.65		mΩ



### Part number

- M = Module
- I = IGBT
- X = XPT IGBT
- A = Gen 1 / std
- 600 = Current Rating [A]
- PF = Phase leg + free wheeling Diodes
- 650 = Reverse Voltage [V]
- T = Thermistor \ Temperature sensor
- SF = SimBus F

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MIXA600PF650TSF	MIXA600PF650TSF	Box	3	513794

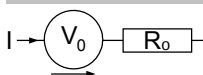
### Temperature Sensor NTC

Symbol	Definition	Conditions	min.	typ.	max.	Unit
$R_{25}$	resistance	$T_{VJ} = 25^\circ$	4.75	5	5.25	kΩ
$B_{25/50}$	temperature coefficient			3375		K

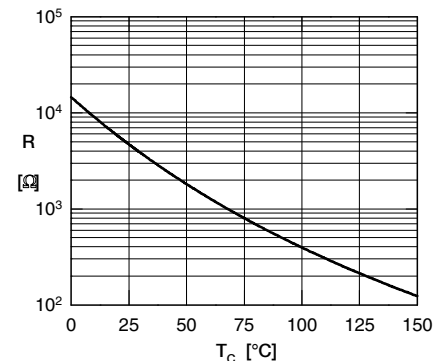
### Equivalent Circuits for Simulation

\* on die level

$T_{VJ} = 175^\circ\text{C}$



		IGBT	Diode	
$V_{0\ max}$	threshold voltage	1.1	1.21	V
$R_{0\ max}$	slope resistance *	1.8	1	mΩ



Outlines SimBus F

